

Statement of Compliance

Requested Part

12 June 2023	W57-XB1A4	IA10-20	(Part 1 of 1)	
	TE Internal Number:	4-1423675-0		
	Product Description:	W57-XB1A4A10-20=CKTBKR,THE	RM,P	
	Part Status:	Active		
	Mil-Spec Certified:	No		
	EU RoHS Directive 2011/65/EU:	Not Compliant		
		Substances: Cd		

This declaration covers EU Directive 2011/65/EU incl. Delegated Directive 2015/863/EU.

China RoHS 2 Directive: MIIT Order No 32, 2016Sestricted Materials Above ThresholdEU REACH Regulation: (EC) No. 1907/2006Current ECHA Candidate List: JAN 2023 (233) Candidate List Declared Against: JAN 2023 (233) SVHC > Threshold: TBBPA (17% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.Halogen Content:Not Low Halogen - contains Br or Cl > 900 ppm.Solder Process Capability Code: Material Declarations:MD_4-1423675-0 MD_4-1423675-0	EU ELV Directive: 2000/53/EC	Not Compliant Substances: Cd
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	Solder Process Capability Code:	Not applicable for solder process capability
MD_4-1423675-0	Material Declarations:	MD_4-1423675-0
		MD_4-1423675-0

TE Connectivity Corporation

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This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change.

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.

Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV).

Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

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Restricted Materials Above Threshold

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中国电子电气产品中有害物质的名称及含量

China EEP Hazardous Substance Information

部件名称			有	ī害物质			
(Component Name)	Hazardous Substance						
4-1423675-0	铅	汞	镉	六价铬	多溴联苯	多溴二苯酸	
	(Pb)	(Hg)	(Cd)	(Cr6)	(PBB)	(PBDE)	
继电器	0	0	X	0	0	0	
(Relays)							
本表格依据SJ/T 1136 O: 表示该有害物质在	该部件所有均质	质材料中的含量	_均在GB/T 265	572标准规定的	限量要求以下。		
	该部件所有均质	质材料中的含量	_均在GB/T 265	572标准规定的	限量要求以下。		
O: 表示该有害物质在:	该部件所有均质 concentration c	贡材料中的含量 of the hazardou	均在GB/T 265 us substance i	572标准规定的	限量要求以下。		
O: 表示该有害物质在 Indicates that the o	该部件所有均质 concentration c threshold of th	质材料中的含量 of the hazardou ne GB/T 26572	均在GB/T 265 us substance i standard.	572标准规定的 n all homogen	限量要求以下。 eous materials	of the part is	
O: 表示该有害物质在 Indicates that the o below the relevant	该部件所有均质 concentration c threshold of th 少在该部件的事 concentration c	质材料中的含量 of the hazardou ne GB/T 26572 其一均质材料中 of the hazardou	均在GB/T 265 us substance i standard. 的含量超出GI us substance i	572标准规定的 n all homogen 3/T 26572标准 n at least one	限量要求以下。 eous materials 规定的限量要系	of the part is ҟ₀	

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